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• Contact - Rated Current = 7.5 A

Socket Length = 7.32 mm

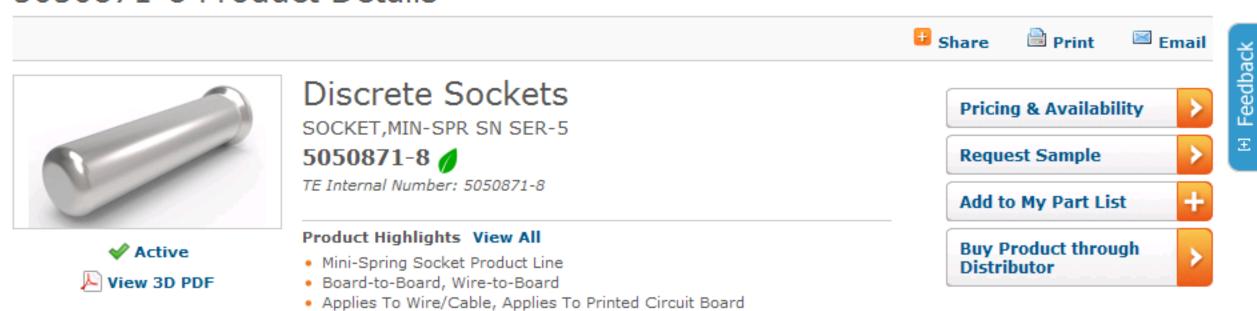
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5050871-8 Product Details



Documents Features	Compliance		
Please Note: Use the Product Drawing for all design activity			
Product Type Features		Contact Features	
Product Line	Mini-Spring Socket	Contact Spring Plating	Tin
Sleeve Style ?	Closed Bottom	Contact Plating, Mating	
Sealant ?	Without	Area, Material	Tin
Wire/Cable Type	Discrete Wire	Contact Plating, Mating Area, Thickness (µm	0.00254 [0.1]
Product Series Profile	Zero	[µin]) Contact Type	Socket
Profile	2610	Contact Base Material	Beryllium Copper
Electrical Characteristics		contact base natorial	эсгунанг сорраг
Contact - Rated	7.5	Industry Standards	
Current (A)		Government/Industry Qualification	No
Termination Features		RoHS/ELV Compliance	RoHS compliant, ELV compliant
Wire/Cable Size (mm²)			Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste
Wire/Cable Size (AWG)			
Insertion Method ?	Hand/Semi-Automatic	Lead Free Solder	
Wire/Cable Termination Method to	Solder Through Hole - Press Fit	Processes ?	
PC Board	Through Hole - Press He		capable to 260°C
Dimensions		RoHS/ELV Compliance History	Always was RoHS compliant
Socket Length (mm [in])	7.32 [0.288]	Environmental	
Recommended Hole Size (mm [in])	2.56 [0.101]	Operating Temperature (°C [°F])	-65 - +126 [-85 - +258]
PCB Thickness, Recommended (mm [in])	0.79 - 3.18 [0.031 - 0.125]	Conditions for Usage	
Body Features		Applies To	Wire/Cable, Printed Circuit Board
Mating Pin Dia. Range (mm [in])	1.07 - 1.24 [0.042 - 0.049]	Operation/Application	
Sleeve Material Plating	Tin	Application Use	Board-to-Board, Wire-to-Board
Wire Type	Solid	Contact Transmits (Typical Application)	Signal (Data)/Power
Sleeve Material	Copper	Application	Production
Spring Material	Beryllium Copper		
		Packaging Features	
		Packaging Method	Loose Piece
		Packaging Quantity	2,000/Bag
		Other	
		Brand	AMP

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